
2SB561

Silicon PNP Epitaxial

HITACHI

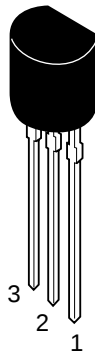
ADE-208-1023 (Z)
1st. Edition
Mar. 2001

Application

- Low frequency power amplifier
- Complementary pair with 2SD467

Outline

TO-92 (1)



1. Emitter
2. Collector
3. Base

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	-25	V
Collector to emitter voltage	V_{CEO}	-20	V
Emitter to base voltage	V_{EBO}	-5	V
Collector current	I_C	-0.7	A
Collector peak current	$i_{C(peak)}$	-1.0	A
Collector power dissipation	P_C	0.5	W
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

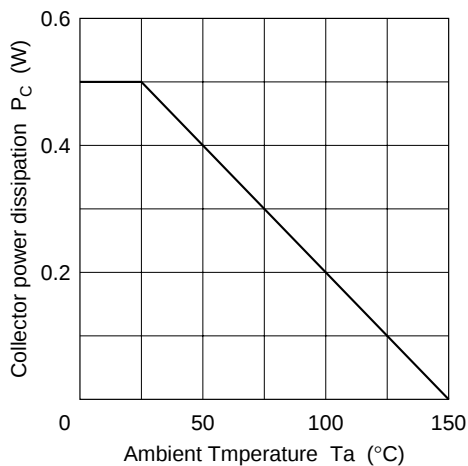
Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-25	—	—	V	$I_C = -10\ \mu A, I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-20	—	—	V	$I_C = -1\ mA, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-5	—	—	V	$I_E = -10\ \mu A, I_C = 0$
Collector cutoff current	I_{CBO}	—	—	-1.0	μA	$V_{CB} = -20\ V, I_E = 0$
DC current transfer ratio	h_{FE}^{*1}	85	—	240		$V_{CE} = -1\ V,$ $I_C = -0.15\ A$ (Pulse test)
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	-0.2	-0.5	V	$I_C = -0.5\ A, I_B = -0.05\ A$
Base to emitter voltage	V_{BE}	—	-0.75	-1.0	V	$V_{CE} = -1\ V, I_C = -0.15\ A$
Gain bandwidth product	f_T	—	350	—	MHz	$V_{CE} = -1\ V, I_C = -0.15\ A$
Collector output capacitance	C_{ob}	—	20	—	pF	$V_{CB} = -10\ V, I_E = 0$ $f = 1\ MHz$

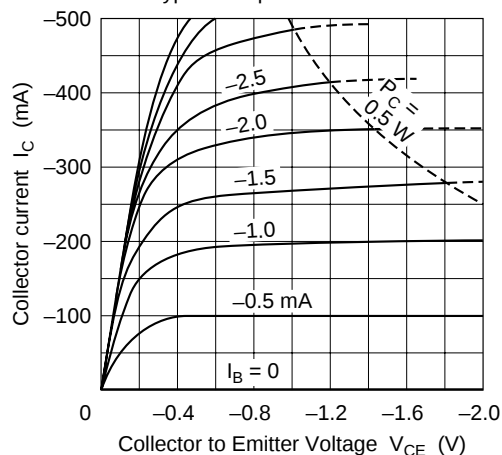
Note: 1. The 2SB561 is grouped by h_{FE} as follows.

B	C
85 to 170	120 to 240

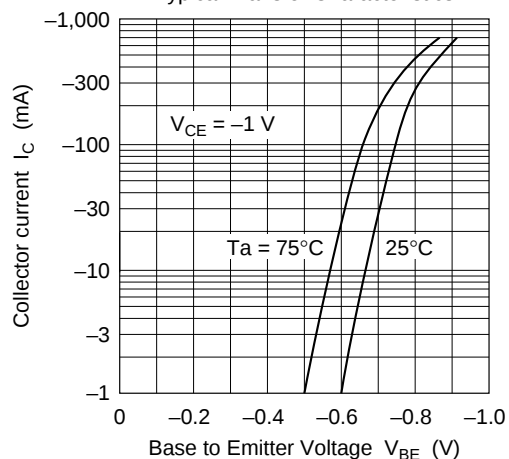
Maximum Collector Dissipation Curve



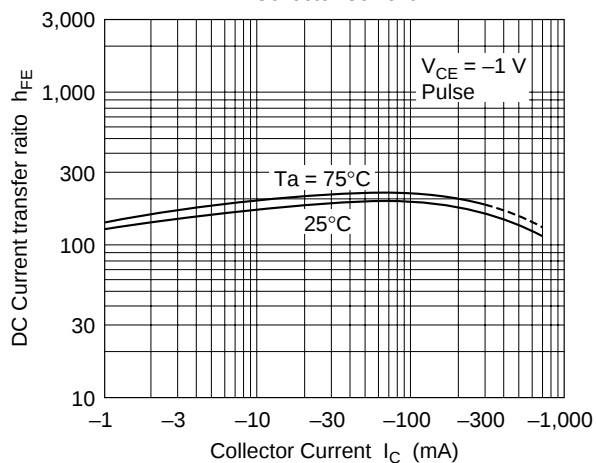
Typical Output Characteristics

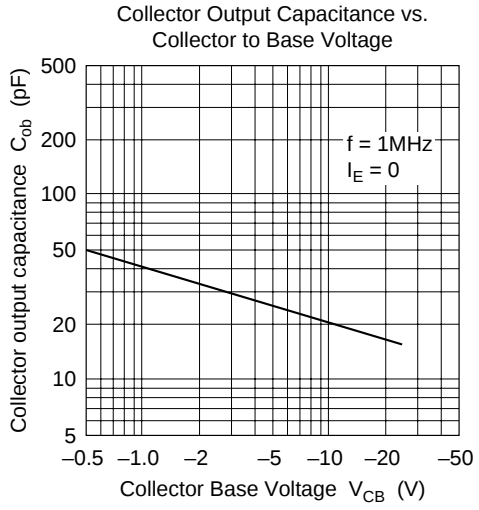
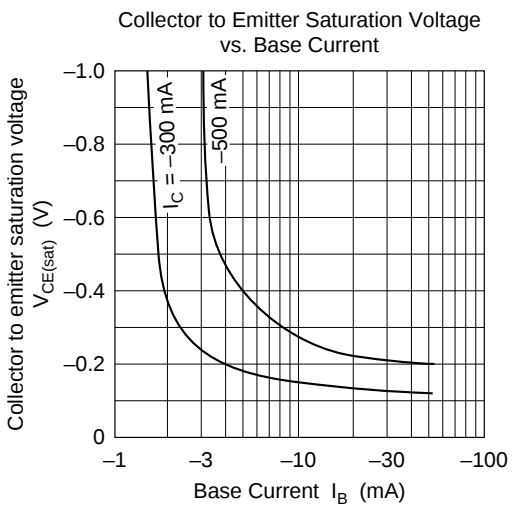
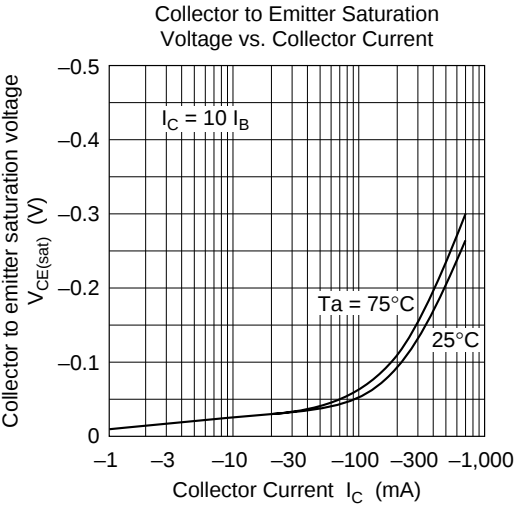


Typical Transfer Characteristics



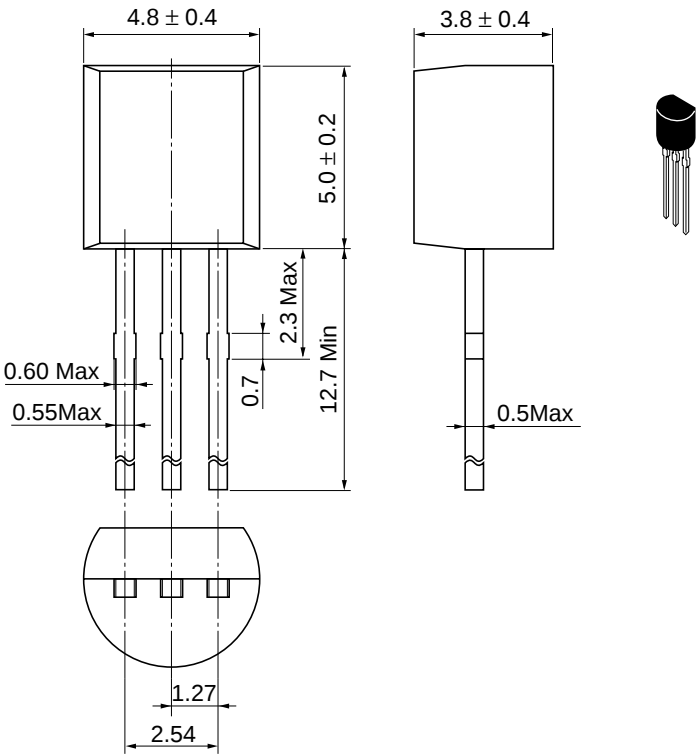
DC Current Transfer Ratio vs. Collector Current





Package Dimensions

As of January, 2001
Unit: mm



Hitachi Code	TO-92 (1)
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.25 g

Cautions

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